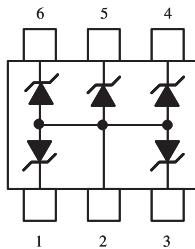




# PJESDA5V6-5G SERIES

## QUAD ARRAY FOR ESD PROTECTION

### DATA



### MAXIMUM RATINGS (T<sub>A</sub>=25°C unless otherwise noted)

Parameter	Symbol	Limits	Unit
Peak Power Dissipation (8x20μs@T <sub>A</sub> =25°C)(Note 1)	P <sub>PK</sub>	40	W
Steady State Power-1Diode (Note 2)	P <sub>D</sub>	300	mW
Thermal Resistance Junction to Ambient Above 25°C,Derate	R <sub>θJA</sub>	370 2.7	°C/W mW/°C
Lead Solder Temperature (10 seconds duration)	T <sub>L</sub>	260	°C
Operating Junction and Storage Temperature Range	T <sub>J</sub> ,T <sub>STG</sub>	-55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

### ELECTRICAL CHARACTERISTICS (T<sub>A</sub>=25°C)

Part Number	Breakdown Voltage V <sub>BR</sub> @1mA (Volts)			Leakage Current I <sub>RM</sub> @V <sub>RM</sub>		V <sub>c</sub> Max@I <sub>PP</sub>		Max Capacitance @0V Bias (1MHz)	Marking
	Min	Nom	Max	V <sub>RWM</sub>	I <sub>RWM</sub>	V <sub>c</sub>	I <sub>PP</sub>		
	V	V	V	V	μA	V	A		
PJESDA5V6-5G	5.32	5.6	5.88	3.0	1	10	5.0	45	SQ
PJESDA6V2-5G	5.89	6.2	6.51	4.3	1	11	4.5	40	ST
PJESDA6V8-5G	6.37	6.7	7.04	5.0	1	12	4.0	35	SU

1. Non-repetitive current per Figure 1.

2. Only 1 diode under power. For all 4 diodes under power, P<sub>D</sub> will be 25%. Mounted on FR-4 board with min pad